

21-Bit Deserializers with Programmable Spread Spectrum and DC Balance

General Description

The MAX9242/MAX9244/MAX9246 deserialize three LVDS serial-data inputs into 21 single-ended LVCMOS/ LVTTL outputs. A separate parallel-rate LVDS clock provides the timing for deserialization. The MAX9242/ MAX9244/MAX9246 feature spread-spectrum capability, allowing the output data and clock frequency to spread over a specified range to reduce EMI. The single-ended data and clock outputs are programmable for a frequency spread of $\pm 2\%$, $\pm 4\%$, or no spread. The spread-spectrum function is also available when the MAX9242/MAX9244/MAX9246 operate in non-DC-balanced mode. The modulation rate of the spread is 32kHz for a 33MHz LVDS clock input and scales linearly with frequency. The single-ended outputs have a separate supply, allowing +1.8V to +5V output logic levels.

The MAX9242/MAX9244/MAX9246 feature programmable DC balance, allowing isolation between a serializer and deserializer using AC-coupling. The MAX9242/ MAX9244/MAX9246 operate with the MAX9209/ MAX9213 serializers and are available with a risingedge strobe (MAX9242) or falling-edge strobe (MAX9244/MAX9246). The LVDS inputs meet ISO 10605 ESD specifications with ±30kV Air-Gap Discharge and ±6kV Contact Discharge ratings.

The MAX9242/MAX9244/MAX9246 are available in a 48-pin TSSOP package and operate over the -40°C to +85°C temperature range.

Applications

Automotive Navigation Systems Automotive DVD Entertainment Systems Digital Copiers Laser Printers

			FREQUENC	CY RANGE
PART	STROBE EDGE	OVER- SAMPLING	NON-DC BALANCE (MHz)	DC BALANCE (MHz)
MAX9242	Rising	Yes	20 to 40	16 to 34
MAX9244	Falling	Yes	20 to 40	16 to 34
MAX9246	Falling	No	8 to 20	6 to 18

M/X/M

Selector Guide

_Features

- Programmable ±4%, ±2%, or OFF Spread-Spectrum Output for Reduced EMI
- Programmable DC-Balanced or Non-DC-Balanced Modes
- DC Balance Allows AC-Coupling for Wider Input Common-Mode Voltage Range
- Spread Spectrum Operates in DC-Balanced or Non-DC-Balanced Mode
- π / 4 Deskew by Oversampling (MAX9242/MAX9244)
- 16MHz-to-34MHz (DC-Balanced) and 20MHz-to-40MHz (Non-DC-Balanced) Operation (MAX9242/MAX9244)
- 6MHz-to-18MHz (DC-Balanced) and 8MHz-to-20MHz (Non-DC-Balanced) Operation (MAX9246)
- Rising-Edge (MAX9242) or Falling-Edge (MAX9244/MAX9246) Output Strobe
- High-Impedance Outputs when PWRDWN is Low Allow Output Busing
- ♦ Fail-Safe Inputs in Non-DC-Balanced Mode
- Separate Output Supply Allows Interface to +1.8V, +2.5V, +3.3V, and +5V Logic
- LVDS Inputs Meet ISO 10605 ESD Protection at ±30kV Air-Gap Discharge and ±6kV Contact Discharge
- LVDS Inputs Meet IEC 61000-4-2 Level 4 ESD Protection at ±15kV Air-Gap Discharge and ±8kV Contact Discharge
- LVDS Inputs Conform to ANSI TIA/EIA-644 Standard
- ♦ +3.3V Main Power Supply

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	PKG CODE
MAX9242EUM	-40°C to +85°C	48 TSSOP	U48-1
MAX9244EUM	-40°C to +85°C	48 TSSOP	U48-1
MAX9246EUM	-40°C to +85°C	48 TSSOP	U48-1

Devices are available in lead-free packaging. Specify lead free by adding a + symbol at the end of the part number when ordering.

Pin Configuration appears at end of data sheet.

_ Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

(All voltages referenced to GND.)

(All voltages references to GIVD.)		
VCC, LVDSVCC, PLLVCC	0.5V to +4.0V	LVDS
V _{CCO}	0.5V to +6.0V	LVDS I
RxIN_, RxCLKIN	0.5V to +4.0V	ISO 106
PWRDWN	0.5V to +6.0V	LVDS
SSG, DCB	0.5V to (V _{CC} + 0.5V)	LVDS I
RxOUT_, RxCLKOUT	0.5V to (V _{CCO} + 0.5V)	Operating
Continuous Power Dissipation ($T_A =$	+70°C)	Storage
48-Pin TSSOP (derate 16mW/°C a	above +70°C)1282mW	Junction
ESD Protection		Lead Ter
Human Body Model ($R_D = 1.5 k\Omega$, ($C_{\rm S} = 100 {\rm pF}$)	
All Pins to GND	+2.5kV	

IEC 61000-4-2 (R _D = 330Ω, C _S = 150pF)	
LVDS Inputs to GND (Air-Gap Discharge)	±15kV
LVDS Inputs to GND (Contact Discharge)	±8kV
ISO 10605 ($R_D = 2.0 k\Omega$, $C_S = 330 pF$)	
LVDS Inputs to GND (Air-Gap Discharge)	±30kV
LVDS Inputs to GND (Contact Discharge)	±6kV
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = LVDSV_{CC} = PLLV_{CC} = +3.0V$ to +3.6V, $V_{CCO} = +3.0V$ to +5.5V, $\overline{PWRDWN} = high$; SSG = high, open, or low; DCB = high or low, differential input voltage $|V_{ID}| = 0.05V$ to 1.2V, input common-mode voltage $V_{CM} = |V_{ID}| / 2l$ to 2.4V - $|V_{ID}| / 2l$, unless otherwise noted. Typical values are at $V_{CC} = V_{CCO} = LVDSV_{CC} = PLLV_{CC} = +3.3V$, $|V_{ID}| = 0.2V$, $V_{CM} = +1.25V$, $T_A = +25^{\circ}C$.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS			MIN	ТҮР	MAX	UNITS
POWER SUPPLY		·						
Power-Supply Range	V _{CC} , LVDSV _{CC} , PLLV _{CC}				3.0		3.6	V
Output-Supply Range	Vcco				1.8		5.5	V
			DC-balanced	16MHz		45	61	
		C _L = 8pF, worst-case pattern, V _{CC} = V _{CCO} = 3.0V	mode (SSG = low)	34MHz		72	96	
			Non-DC-balanced mode (SSG = low)	20MHz		59	79	
				33MHz		80	106	
Warst Case Supply Current				40MHz		93	123	
Worst-Case Supply Current	ICCW	to 3.6V, Figure 2	DC-balanced mode	16MHz		57	78	mA
		(MAX9242,	(SSG = high or open)	34MHz		93	125	
		MAX9244)	Non-DC-balanced	20MHz		71	96	
			mode	33MHz		98	129	
			(SSG = high or open)	40MHz		115	145	

DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = LVDSV_{CC} = PLLV_{CC} = +3.0V$ to +3.6V, $V_{CCO} = +3.0V$ to +5.5V, $\overline{PWRDWN} = high$; SSG = high, open, or low; DCB = high or low, differential input voltage $|V_{ID}| = 0.05V$ to 1.2V, input common-mode voltage $V_{CM} = |V_{ID}| / 2I$ to 2.4V - $|V_{ID}| / 2I$, unless otherwise noted. Typical values are at $V_{CC} = V_{CCO} = LVDSV_{CC} = PLLV_{CC} = +3.3V$, $|V_{ID}| = 0.2V$, $V_{CM} = +1.25V$, $T_A = +25^{\circ}C$.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS			MIN	TYP	MAX	UNITS
				6MHz		27	41	
			DC-balanced	8MHz		30	45	
			mode (SSG = low)	18MHz		43	61	
				8MHz		33	47	
		C _L = 8pF,	Non-DC-balanced	10MHz		37	52	
		worst-case pattern,	mode (SSG = low)	20MHz		52	73	
Worst-Case Supply Current	ICCW	$V_{CC} = V_{CCO} = 3.0V$ to 3.6V, Figure 2		6MHz		32	47	mA
		(MAX9246)	DC-balanced mode	8MHz		38	57	
		`	(SSG = high or open)	18MHz		57	81	
			Non-DC-balanced	8MHz		41	58	
			mode	10MHz		46	65	
			(SSG = high or open)	20MHz		66	92	ĺ
Power-Down Supply Current	Iccz	PWRDWN = low					50	μA
5V-TOLERANT LOGIC INPUT	WRDWN)	•						
High-Level Input Voltage	VIH				2.0		5.5	V
Low-Level Input Voltage	VIL				-0.3		+0.8	V
Input Current	I _{IN}	$\overline{PWRDWN} = high or$	low level		-20		+20	μA
Input Clamp Voltage	V _{CL}	I _{CL} = -18mA			-1.5			V
THREE-LEVEL LOGIC INPUTS	(DCB, SSG)	•						
High-Level Input Voltage	VIH				2.5		V _{CC} + 0.3	V
Mid-Level Input Current	IIM	DCB, SSG open or co output in high-impeda	onnected to a driver wi ance state (Note 3)	th	-10		+10	μA
Low-Level Input Voltage	VIL				-0.3		+0.8	V
Input Current	l _{IN}	DCB, SSG = high or $\overline{PWRDWN} = high or$			-20		+20	μA
Input Clamp Voltage	V _{CL}	I _{CL} = -18mA			-1.5			V
SINGLE-ENDED OUTPUTS (Rx		-						
					Vcco			
		I _{OH} = -100μA			- 0.1			
High-Level Output Voltage	V _{OH}		RxCLKOUT (Note	4)	V _{CCO} - 0.25			V
		$I_{OH} = -2mA$	RxOUT_		V _{CCO} - 0.43			
		I _{OL} = 100μΑ					0.1	
Low-Level Output Voltage	Vol		RxCLKOUT (Note	4)			0.2	V
-		I _{OL} = 2mA RXOUT_					0.26	1

DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = LVDSV_{CC} = PLLV_{CC} = +3.0V$ to +3.6V, $V_{CCO} = +3.0V$ to +5.5V, $\overline{PWRDWN} = high$; SSG = high, open, or low; DCB = high or low, differential input voltage $|V_{ID}| = 0.05V$ to 1.2V, input common-mode voltage $V_{CM} = IV_{ID} / 2I$ to 2.4V - $IV_{ID} / 2I$, unless otherwise noted. Typical values are at $V_{CC} = V_{CCO} = LVDSV_{CC} = PLLV_{CC} = +3.3V$, $|V_{ID}| = 0.2V$, $V_{CM} = +1.25V$, $T_A = +25^{\circ}C$.) (Notes 1, 2)

PARAMETER	SYMBOL	CO	NDITIONS	MIN	ТҮР	MAX	UNITS
High-Impedance Output Current	IOZ	PWRDWN = low, Vout	$ = -0.3V \text{ to } (V_{CCO} + 0.3V) $	-30		+30	μA
		V _{CCO} = 3.0V to 3.6V,	RxCLKOUT (Note 4)	-10		-40	
Output Short-Circuit Current		$V_{OUT} = 0V$	RxOUT_	-5		-20	
(Note 5)	los	VCCO = 4.5V to 5.5V,	RxCLKOUT (Note 4)	-28		-75	mA
		VOUT = 0V	RxOUT_	-13		-37	
LVDS INPUTS (RxIN_, RxCLKIN_)							
Differential Input High Threshold	V _{TH}	(Note 6)				50	mV
Differential Input Low Threshold	V _{TL}	(Note 6)		-50			mV
Input Current	I _{IN+} , I _{IN-}	\overline{PWRDWN} = high or low	N	-25		+25	μA
Power-Off Input Current	I _{INO+} , I _{INO-}	$V_{CC} = V_{CCO} = 0V$ or o	pen	-40		+40	μA
Input Resistor 1	RIN1	\overline{PWRDWN} = high or low, V _{CC} = V _{CCO} = 0V or open, Figure 1		42		78	kΩ
Input Resistor 2	R _{IN2}	$\overline{\text{PWRDWN}}$ = high or low, V _{CC} = V _{CCO} = 0V or open, Figure 1		246		410	kΩ

AC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = LVDSV_{CC} = PLLV_{CC} = +3.0V$ to +3.6V, $V_{CCO} = +3.0V$ to +3.6V, $C_{L} = 8pF$, $\overline{PWRDWN} = high$; SSG = high, open, or low; DCB = high or low, differential input voltage $|V_{ID}| = 0.1V$ to 1.2V, input common-mode voltage $V_{CM} = |V_{ID}| / 2I$ to $2.4V - |V_{ID}| / 2I$, unless otherwise noted. Typical values are at $V_{CC} = V_{CCO} = LVDSV_{CC} = PLLV_{CC} = +3.3V$, $|V_{ID}| = 0.2V$, $V_{CM} = +1.25V$, $T_A = +25^{\circ}C$.) (Notes 6, 7, 8)

PARAMETER	SYMBOL	CONDITION	IS	MIN	ТҮР	MAX	UNITS
	CLHT	0.1 x VCCO to 0.9 x VCCO,	RxOUT_	2.9	4.7	6.5	
Output Rise Time	CLHI	Figure 3	RxCLKOUT	2.0	3.3	4.1	ns
Output Fall Time	CHLT	0.9 x V _{CCO} to 0.1 x V _{CCO} ,	RxOUT_	2.1	3.0	4.2	ns
	CHLI	Figure 3	RxCLKOUT	1.10	1.94	2.70	ns
		DC-balanced mode,	16MHz	2560	3142		
RxIN Skew Margin (Note 9)	RSKM	Figure 4	34MHz	900	1386		D 0
nxin skew Margin (Note 9)	ROVIN	Non-DC-balanced mode, Figure 4	20MHz	2500	3164		ps -
			40MHz	960	1371		
RxCLKOUT High Time	RCOH	Figures 5a, 5b		0.35 x RCOP			ns
RxCLKOUT Low Time	RCOL	Figures 5a, 5b		0.35 x RCOP			ns
RXOUT Setup to RXCLKOUT	RSRC	Figures 5a, 5b		0.3 x RCOP			ns
RXOUT Hold from RXCLKOUT	RHRC	Figures 5a, 5b		0.45 x RCOP			ns
RxCLKIN to RxCLKOUT Delay	RCCD	SSG = low, Figures 6a, 6b		4.5 + (RCIP / 2)	6.5 + (RCIP / 2)	8.2 + (RCIP / 2)	ns

AC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = LVDSV_{CC} = PLLV_{CC} = +3.0V$ to +3.6V, $V_{CCO} = +3.0V$ to +3.6V, $C_L = 8pF$, $\overline{PWRDWN} = high; SSG = high, open, or low; DCB = high or low, differential input voltage <math>|V_{ID}| = 0.1V$ to 1.2V, input common-mode voltage $V_{CM} = |V_{ID}| / 2I$ to 2.4V - $|V_{ID}| / 2I$, unless otherwise noted. Typical values are at $V_{CC} = V_{CCO} = LVDSV_{CC} = PLLV_{CC} = +3.3V$, $|V_{ID}| = 0.2V$, $V_{CM} = +1.25V$, $T_A = +25^{\circ}C$.) (Notes 6, 7, 8)

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PARAMETER	SYMBOL	CON	DITIONS	MIN	ТҮР	MAX	UNITS
Deserializer Phase-Locked- Loop Set	RPLLS	Figure 7				65,600 x RCIP	ns
Deserializer Power-Down Delay	RPDD	Figure 8				100	ns
Deserializer Phase-Locked- Loop Set from SSG Change	RPLLS2	Figure 9				32,800 x RCIP	ns
		SSG = high,	Maximum output frequency	f _{RxCLKIN} + 3.6%	f _{RxCLKIN} + 4.0%	f _{RxCLKIN} + 4.4%	
Spread-Spectrum Output Frequency		Figure 10	Minimum output frequency	fRxCLKIN - 4.4%	f _{RxCLKIN} - 4.0%	f _{RxCLKIN} - 3.6%	_
	f _{RxCLKOUT}	SSG = open,	Maximum output frequency	fRxCLKIN + 1.8%	f _{RxCLKIN} + 2.0%	f _{RxCLKIN} + 2.2%	MHz
		Figure 10	Minimum output frequency	fRxCLKIN - 2.2%	f _{RxCLKIN} - 2.0%	f _{RxCLKIN} - 1.8%	_
		SSG = low		f RxCLKIN		f RxCLKIN	
Spread-Spectrum Modulation Frequency	fssm	Figure 10			f _{RxCLKIN} / 1016		Hz

Note 1: Current into a pin is defined as positive. Current out of a pin is defined as negative. All voltages are referenced to ground, except V_{TH} and V_{TL}.

Note 2: Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are production tested at $T_A = +25^{\circ}C$.

Note 3: To provide a mid level, leave the input open, or, if driven, put driver in high impedance. High-impedance leakage current must be less than ±10μA.

Note 4: RxCLKOUT limits are scaled based on RxOUT_ measurements, design, and characterization data.

Note 5: One output shorted at a time. Current out of the pin.

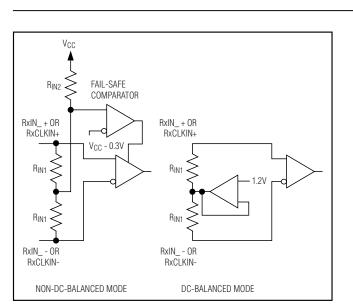
Note 6: V_{TH}, V_{TL}, and AC parameters are guaranteed by design and characterization, and are not production tested. Limits are set at ±6 sigma.

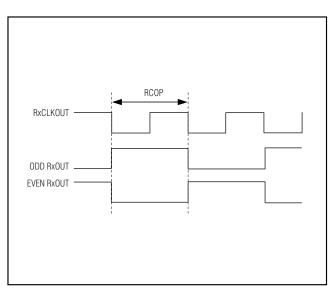
Note 7: C_L includes probe and test jig capacitance.

Note 8: RCIP is the period of RxCLKIN. RCOP is the period of RxCLKOUT.

Note 9: RSKM is measured with less than 150ps cycle-to-cycle jitter on RxCLKIN.







Test Circuits/Timing Diagrams

Figure 2. Worst-Case Test Pattern

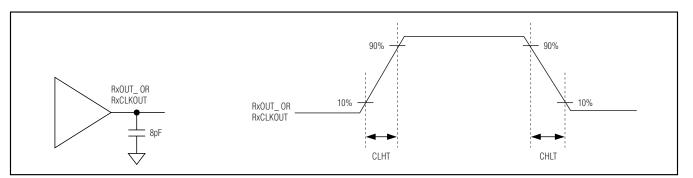


Figure 3. Output Load and Transition Times

Figure 1. LVDS Input Circuits

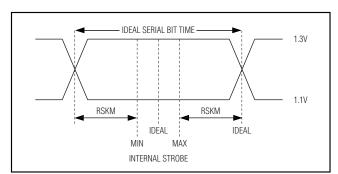
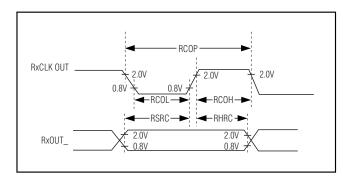
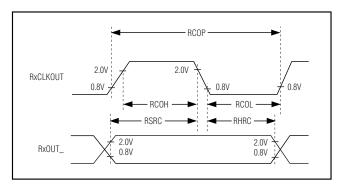


Figure 4. LVDS Receiver Input Skew Margin







Test Circuits/Timing Diagrams (continued)

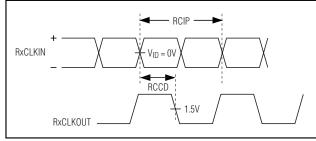


Figure 5b. Falling-Edge Output Setup/Hold and High/Low Times

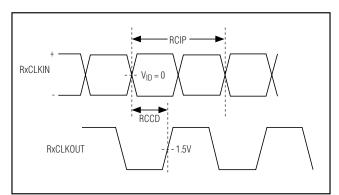


Figure 6b. Clock-IN to Clock-OUT Delay (MAX9242)

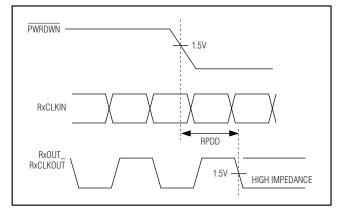
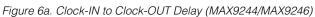


Figure 8. Power-Down Delay



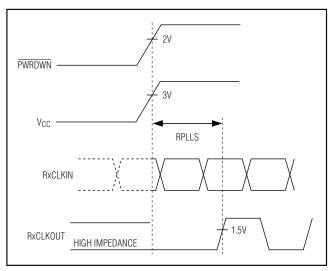


Figure 7. Phase-Locked-Loop Set Time

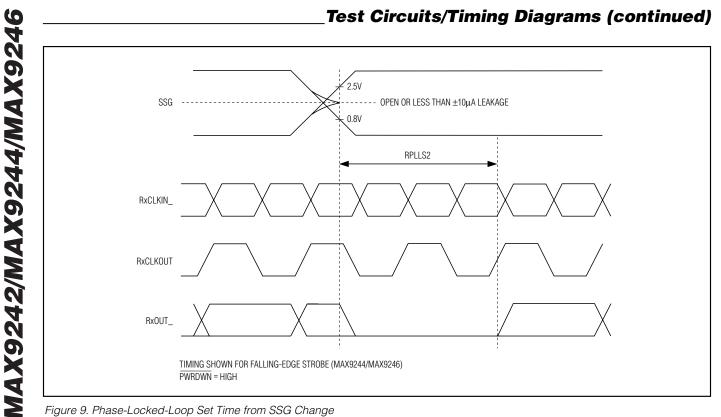


Figure 9. Phase-Locked-Loop Set Time from SSG Change

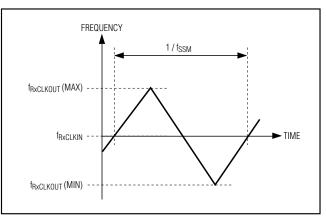
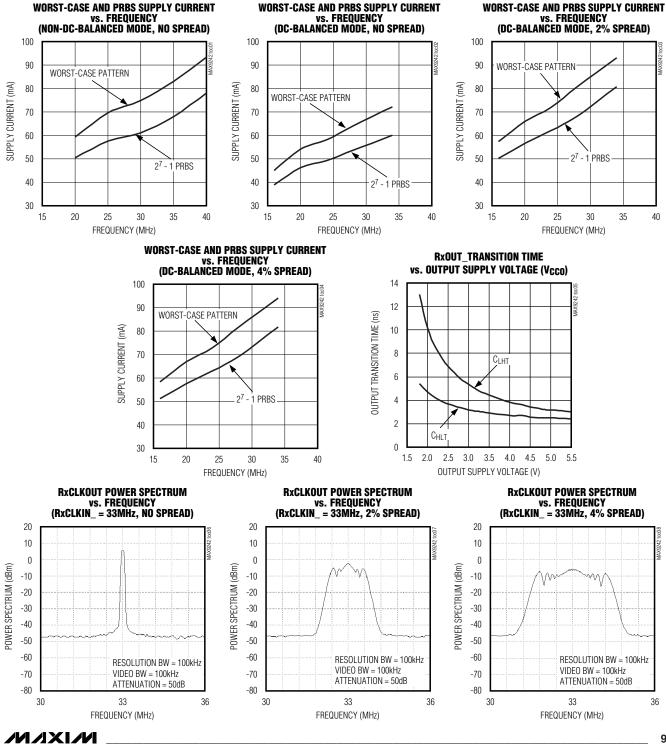
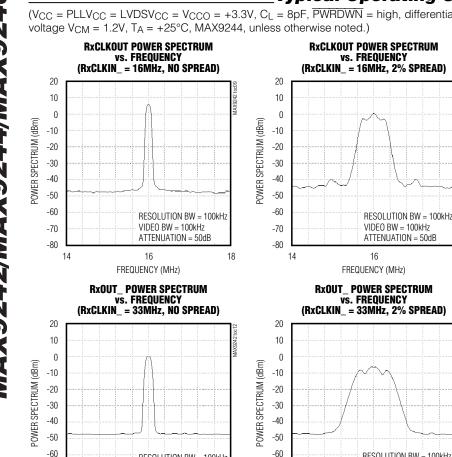


Figure 10. Simplified Modulation Profile

Typical Operating Characteristics

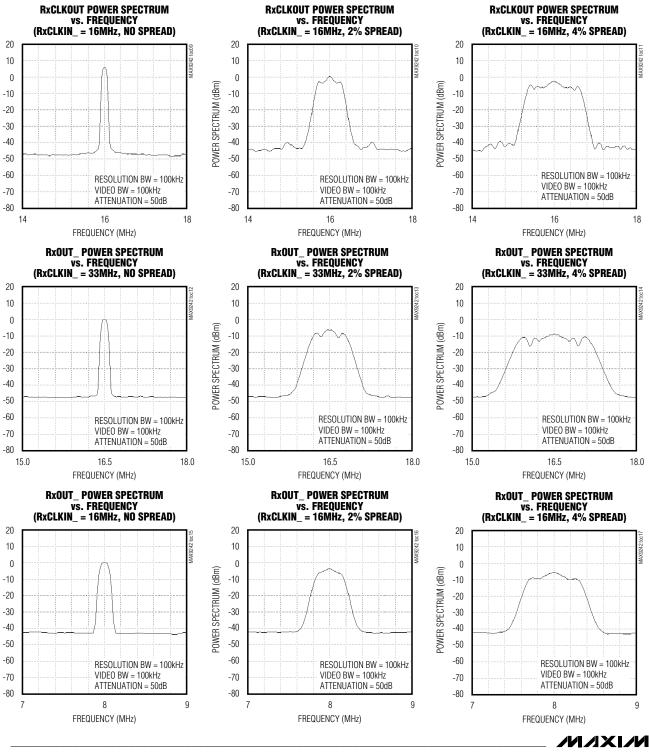
(V_{CC} = PLLV_{CC} = LVDSV_{CC} = V_{CCO} = +3.3V, C_L = 8pF, PWRDWN = high, differential input voltage IV_{ID}I = 0.2V, input common-mode voltage $V_{CM} = 1.2V$, $T_A = +25^{\circ}C$, MAX9244, unless otherwise noted.)





Typical Operating Characteristics (continued)

(V_{CC} = PLLV_{CC} = LVDSV_{CC} = V_{CCO} = +3.3V, C_L = 8pF, PWRDWN = high, differential input voltage IV_{ID}I = 0.2V, input common-mode



(dBm)

POWER SPECTRUM

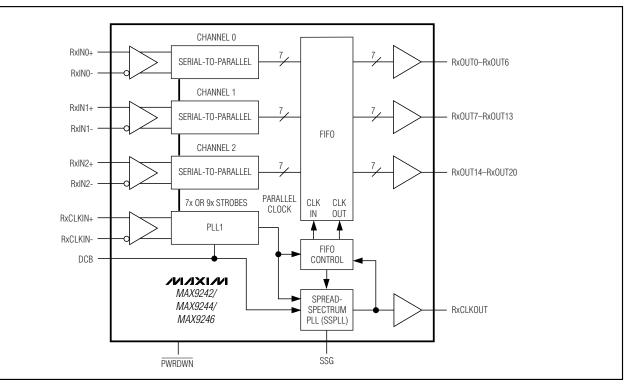
_Pin Description

PIN NAME FUNCTION 1 RxOUT10 Channel 2 Single-Ended Outputs 3,25,32,38,44 GND Ground 4 RxOUT20 Channel 2 Single-Ended Outputs 5 RxOUT30 Channel 2 Single-Ended Outputs 5 RxOUT30 Channel 2 Single-Ended Outputs 5 RxOUT30 Channel 2 Single-Ended Outputs 6 SSG Three-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 10 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 11 BxIN4- Noninverting Channel 1 LVDS Serial-Data Input 12 LVDS/Cc LVDS Ground 13.18 LVDS Ground RxIN2- 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN+ Inverting Channel 2 LVDS Serial-Data Input			
2 RxOUT18 Channel 2 Single-Ended Outputs 3.25, 32, 38, 44 GND Ground Ground 4 FxOUT20 Channel 2 Single-Ended Outputs 5 RxOLV20 Channel 2 Single-Ended Outputs 6 SSG Three-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN1+ Inverting Channel 1 LVDS Serial-Data Input 10 RxIN1+ Inverting Channel 1 LVDS Serial-Data Input 11 RxIN2- Inverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13. 18 LVDSCND LVDS Grannel 2 LVDS Serial-Data Input 14 RxIN2- Noninverting Channel 2 LVDS Serial-Data Input 17 RxCLKIN+ Noninverting Channel 2 LVDS Serial-Data Input 18 LVDSGRDU LVDS Ground	PIN	NAME	FUNCTION
2 HXOUT18 Final Product Serial-Data Input 3, 25, 32, 38, 44 GND Ground 4 FXOUT20 Channel 2 Single-Ended Outputs 5 FXOUT20 Three-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, CD-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN1+ Noninverting Channel 0 LVDS Serial-Data Input 10 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSGOD LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxILVI- Inverting Channel 2 LVDS Serial-Data Input 16 RxCLKINI- Inverting Channel 2 LVDS Serial-Data Input 17 RxCLKINI- Noninverting LVDS Parallel-Rate Clock Input 18 RxDIX- Inverting Channel 2 LVDS Serial-Data Input 14 RxIN2- Noninverting LVDS Parallel-Rate Clock Input 17 RxCLKINI- <td>1</td> <td>RxOUT17</td> <td>Channel & Single Ended Outputs</td>	1	RxOUT17	Channel & Single Ended Outputs
38, 44 GNU Ground 4 RxOUT19 Channel 2 Single-Ended Outputs 5 RxOUT20 Three-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 10 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Inverting Channel 1 LVDS Serial-Data Input 12 LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Serial-Data Input 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting Channel 2 LVDS Serial-Data Input 17 RxCLKIN- Inverting Channel 2 LVDS Serial-Data Input 18 UVDSGND LVDS Ground Pull 19, 21	2	RxOUT18	Channel 2 Single-Ended Outputs
5 RxOUT20 Channel 2 Single-Ended Outputs 6 SSG Three-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN1- Inverting Channel 0 LVDS Serial-Data Input 10 RxIN1- Noninverting Channel 1 LVDS Serial-Data Input 11 RxIN1- Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Ground 14 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting LVDS Parallel-Rate Clock Input 16 RxCLKIN+ Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLGND PLL Ground 21 PVRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. FWRDWN is inte		GND	Ground
5 RX0U120 Pree-Level-Logic, Spread-Spectrum Generator Control Input. SSG selects the frequency spread of RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RXIN1 Inverting Channel 1 LVDS Serial-Data Input 10 RxIN1 Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Parallel-Rate Clock Input 14 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN+ Inverting Channel 2 LVDS Serial-Data Input 17 RxCLKIN+ Noninverting Channel 2 LVDS Serial-Data Input 18 RxDLW- Noninverting LVDS Parallel-Rate Clock Input 19,21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin	4	RxOUT19	Channel & Cingle Forded Outputs
b SSG RxCLKOUT relative to RxCLKIN (see Table 3). 7 DCB Three-Level-Logic, DC-Balance Control Input. DCB selects DC-balanced, non-DC-balanced, or reserved operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN1+ Inverting Channel 1 LVDS Serial-Data Input 10 RxIN1+ Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDS Ground 14 RxILX- 15 RxILX- 16 RxCLKIN- 17 RxCLKIN- 18 LVDS Serial-Data Input 16 RxCLKIN- 17 RxCLKIN- 18 RxULKIN- 19, 21 PLLGND 20 PLL Ground 21 PLGND 22 PWRDWN 23 RxCLKOUT 24 RxOUT0 25 RxOUT1	5	RxOUT20	Channel 2 Single-Ended Outputs
7 DCB operation (see Table 1). 8 RxIN0- Inverting Channel 0 LVDS Serial-Data Input 9 RxIN0+ Noninverting Channel 0 LVDS Serial-Data Input 10 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Ground 13.18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2- Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting Channel 2 LVDS Serial-Data Input 17 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 19.21 PLLGRUN PLL Ground 20 PLLVcc PLL Ground 21 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 22 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. <	6	SSG	
9 RxIN0+ Noninverting Channel 0 LVDS Serial-Data Input 10 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13. 18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting Channel 2 LVDS Serial-Data Input 17 RxCLKIN+ Noninverting Channel 2 LVDS Serial-Data Input 18 Inverting Channel 2 LVDS Parallel-Rate Clock Input 19. 21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 21 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs <t< td=""><td>7</td><td>DCB</td><td></td></t<>	7	DCB	
10 RxIN1- Inverting Channel 1 LVDS Serial-Data Input 11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxILX+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 21 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT0 Channel 0 Single-Ended Outputs 28 36, 48 Vccco Output Supply Voltage. Bypass each Vcco to GND	8	RxIN0-	Inverting Channel 0 LVDS Serial-Data Input
11 RxIN1+ Noninverting Channel 1 LVDS Serial-Data Input 12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGOND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 21 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a failing-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in paral	9	RxIN0+	Noninverting Channel 0 LVDS Serial-Data Input
12 LVDSVcc LVDS Supply Voltage. Bypass LVDSVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 13, 18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGOND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 21 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Output Su	10	RxIN1-	Inverting Channel 1 LVDS Serial-Data Input
12 LVDSVCc the pin as possible. 13, 18 LVDSGND LVDS Ground 14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLL GND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Channel 0 Single-Ended Outputs 28, 36, 48 Vcco Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs	11	RxIN1+	Noninverting Channel 1 LVDS Serial-Data Input
14 RxIN2- Inverting Channel 2 LVDS Serial-Data Input 15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 26 RxOUT1 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs 31 RXOUT3 Channel 0 Single-Ended Outputs	12	LVDSV _{CC}	
15 RxIN2+ Noninverting Channel 2 LVDS Serial-Data Input 16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 21 PWRDWN 5V-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs 31 RXOUT5 Channel 0 Single-Ended Outputs	13, 18	LVDSGND	LVDS Ground
16 RxCLKIN- Inverting LVDS Parallel-Rate Clock Input 17 RxCLKIN+ Noninverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLVcc PLL Supply Voltage. Bypass PLLVcc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN 5V-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Parallel-Rate Clock Single-Ended Outputs 27 RxOUT2 Channel 0 Single-Ended Outputs 28, 36, 48 Vcco Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Goate to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs 31 RxOUT5 Channel 0 Single-Ended Outputs	14	RxIN2-	Inverting Channel 2 LVDS Serial-Data Input
17 RxCLKIN+ Noniverting LVDS Parallel-Rate Clock Input 19, 21 PLLGND PLL Ground 20 PLLV _{CC} PLL Supply Voltage. Bypass PLLV _{CC} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN SV-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Cutput Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs	15	RxIN2+	Noninverting Channel 2 LVDS Serial-Data Input
19, 21 PLLGND PLL Ground 20 PLLVCC PLL Supply Voltage. Bypass PLLVCc to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN 5V-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 26 RxOUT1 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs	16	RxCLKIN-	Inverting LVDS Parallel-Rate Clock Input
20 PLLV _{CC} PLL Supply Voltage. Bypass PLLV _{CC} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 22 PWRDWN 5V-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Channel 0 Single-Ended Outputs 27 RxOUT2 Channel 0 Single-Ended Outputs 28, 36, 48 V _{CCO} Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs 31 RxOUT3 Channel 0 Single-Ended Outputs	17	RxCLKIN+	Noninverting LVDS Parallel-Rate Clock Input
20 PLLVCC the pin as possible. 22 PWRDWN 5V-Tolerant LVTTL/LVCMOS Power-Down Input. PWRDWN is internally pulled down to GND. Outputs are high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 Parallel-Rate Clock Single-Ended Outputs 26 RxOUT1 Channel 0 Single-Ended Outputs 27 RxOUT2 Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 Channel 0 Single-Ended Outputs 30 RxOUT4 Channel 0 Single-Ended Outputs	19, 21	PLLGND	PLL Ground
22 PWRDWN high impedance when PWRDWN = low or open. 23 RxCLKOUT Parallel-Rate Clock Single-Ended Output. The MAX9242 has a rising-edge strobe. The MAX9244/MAX9246 have a falling-edge strobe. 24 RxOUT0 26 RxOUT1 27 RxOUT2 28, 36, 48 Vcco Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 30 RxOUT4 31 RxOUT5	20	PLLVCC	
23 HXCLKOUT have a falling-edge strobe. 24 RxOUT0 26 RxOUT1 Channel 0 Single-Ended Outputs 27 RxOUT2 28, 36, 48 Vcco Output Supply Voltage. Bypass each Vcco to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 AxOUT4 30 RxOUT4 Channel 0 Single-Ended Outputs	22	PWRDWN	
26 RxOUT1 Channel 0 Single-Ended Outputs 27 RxOUT2 Channel 0 Single-Ended Outputs 28, 36, 48 V _{CCO} Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 30 RxOUT4 31 RxOUT5	23	RxCLKOUT	
27 RxOUT2 28, 36, 48 V _{CCO} Output Supply Voltage. Bypass each V _{CCO} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 30 RxOUT4 31 RxOUT5	24	RxOUT0	
28, 36, 48 VCCO Output Supply Voltage. Bypass each VCCO to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible. 29 RxOUT3 30 RxOUT4 31 RxOUT5	26	RxOUT1	Channel 0 Single-Ended Outputs
28, 36, 48 VCCO close to the pin as possible. 29 RxOUT3 30 RxOUT4 31 RxOUT5	27	RxOUT2	
30 RxOUT4 31 RxOUT5	28, 36, 48	Vcco	
31 RxOUT5 Channel 0 Single-Ended Outputs	29	RxOUT3	
31 RXOUT5	30	RxOUT4	
33 RXOUT6	31	RxOUT5	Unannel U Single-Ended Outputs
	33	RxOUT6	

_Pin Description (continued)

PIN	NAME	FUNCTION
34	RxOUT7	
35	RxOUT8	
37	RxOUT9	Channel 1 Single-Ended Outputs
39	RxOUT10	
40	RxOUT11	
41	RxOUT12	
42	V _{CC}	Digital Supply Voltage. Bypass V_{CC} to GND with 0.1µF and 0.001µF capacitors in parallel as close to the pin as possible.
43	RxOUT13	Channel 1 Single-Ended Output
45	RxOUT14	
46	RxOUT15	Channel 2 Single-Ended Outputs
47	RxOUT16	

Functional Diagram



Detailed Description

The MAX9242/MAX9244/MAX9246 deserialize three LVDS serial-data inputs into 21 single-ended LVCMOS/ LVTTL outputs. The outputs are programmable for no spread or for a spread of $\pm 2\%$ or $\pm 4\%$, relative to the LVDS input clock frequency. The MAX9242/MAX9244 operate at a parallel clock frequency of 16MHz to 34MHz in DC-balanced mode and 20MHz to 40MHz in non-DC-balanced mode. The MAX9246 operates at a 6MHz-to-18MHz parallel clock frequency in DC-balanced mode and 8MHz-to-20MHz parallel clock frequency in non-DC-balanced mode. DC-balanced or non-DC-balanced operation is controlled by the DCB input. The MAX9242 has a rising-edge strobe and the MAX9244/MAX9246 have a falling-edge strobe.

DC Balance (DCB)

DC-balanced or non-DC-balanced operation is controlled by the DCB input (see Table 1). In the non-DCbalanced mode, each channel deserializes 7 bits every cycle of the parallel clock. In DC-balanced mode, 9 bits are deserialized every clock cycle (7 data bits + 2 DC-balanced bits). The highest serial-data rate on each channel in DC-balanced mode is 34MHz x 9 = 306Mbps. In non-DC-balanced mode, the maximum data rate is 40MHz x 7 = 280Mbps.

Table 1. DCB Function

DCB INPUT LEVEL	FUNCTION
High	Non-DC-balanced mode
Mid	Reserved
Low	DC-balanced mode

Data coding by the MAX9209/MAX9213 serializers (that are companion devices to the MAX9242/MAX9244/ MAX9246 deserializers) limits the imbalance of ones and zeros transmitted on each channel. If +1 is assigned to each binary 1 transmitted and -1 is assigned to each binary 0 transmitted, the variation in the running sum of assigned values is called the digital sum variation (DSV). The maximum DSV for the data channels is 10. At most, 10 more zeros than ones, or 10 more ones than zeros, are ever transmitted. The maximum DSV for the clock channel is 5. Limiting the DSV and choosing the correct coupling capacitors maintain differential signal amplitude and reduces jitter due to droop on AC-coupled links.

To obtain DC balance on the data channels, the serializer parallel data is inverted or not inverted, depending on the sign of the digital sum at the word boundary. Two complementary bits are appended to each group of 7 parallel-input data bits to indicate to the MAX9242/ MAX9244/MAX9246 deserializer whether the data bits are inverted (see Figures 11 and 12). The deserializer restores the original state of the parallel data. The LVDS clock signal alternates duty cycles of 4/9 and 5/9 to maintain DC balance.

Spread-Spectrum Generator (SSG)

The MAX9242/MAX9244/MAX9246 single-ended data and clock outputs are programmable for a variation of $\pm 2\%$ or $\pm 4\%$ around the LVDS input clock frequency. The modulation rate of the frequency variation is 32.48kHz for a 33MHz LVDS clock input and scales linearly with the input clock frequency (see Table 2). The spread spectrum can also be turned off. The output spread is controlled through the SSG input (see Table 3).

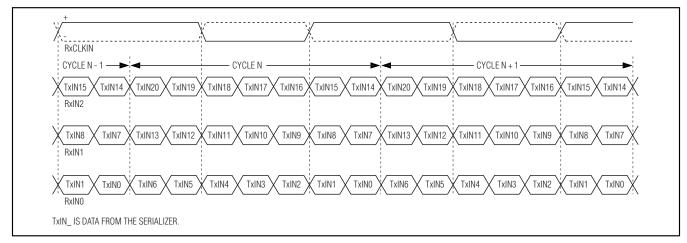


Figure 11. Deserializer Serial Input in Non-DC-Balanced Mode

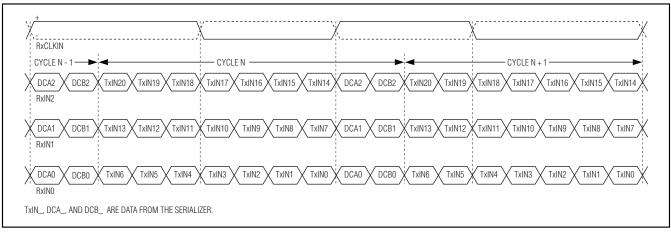


Figure 12. Deserializer Serial Input in DC-Balanced Mode

Table 2.	Modulation	Rate
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f _{RxCLKIN} (MHz)	f _M (kHz) = f _{RxCLKIN} / 1016
6	5.91
8	7.87
10	9.84
16	15.75
18	17.72
20	19.68
33	32.48
34	33.46
40	39.37

Table 3. SSG Function

SSG INPUT LEVEL	FUNCTION
High	RxCLKOUT frequency spread ±4% relative to RxCLKIN
Mid	RxCLKOUT frequency spread ±2% relative to RxCLKIN
Low	No spread on RxCLKOUT relative to RxCLKIN

Note: RxOUT_ data outputs are spread because RxCLKOUT strobes the output of the FIFO.

To select the mid level, leave the input open, or if driven, put the driver output in high impedance. The driver high-impedance leakage current must be less than $\pm 10\mu$ A.

Any spread change causes a maximum delay time of 32,800 x RCIP before output data is valid. When the spread amount is changed from $\pm 2\%$ to $\pm 4\%$ or vice-versa, the data outputs go low for one delay time (see Figure 13). Similarly, when the spread is changed from no spread to $\pm 2\%$ or $\pm 4\%$, the data outputs go low for one delay time (see Figure 14). The data outputs continue to switch but are not valid when the spread amount is changed from $\pm 2\%$ or $\pm 4\%$ to no spread (see Figure 15). The spread-spectrum function is also available when the MAX9242/MAX9244/MAX9246 operate in non-DC-balanced mode.

Hot Swap

When the MAX9242/MAX9244/MAX9246 are connected to an active serializer, they synchronize correctly. The PLL control voltage does not saturate in response to high-frequency glitches that may occur during a hot swap. The PWRDWN input on the MAX9242/MAX9244/ MAX9246 does not need to be cycled when these devices are connected to an active serializer.

PLL Lock Time

The MAX9242/MAX9244/MAX9246 use two PLLs. The first PLL (PLL1) generates a 7x clock (non-DC-balanced mode) or a 9x clock (DC-balanced mode) from RxCLKIN for deserializing the LVDS inputs. The second PLL (SSPLL) is used for spread-spectrum modulation. During initial power-up, the PLL1 locks, and SSPLL locks immediately after. The PLL lock times are set by an internal counter. The maximum time to lock for each PLL is 32,800 clock periods. Power and clock should be stable to meet the lock time specification. After initialization, if the first PLL loses lock, it locks again and then the



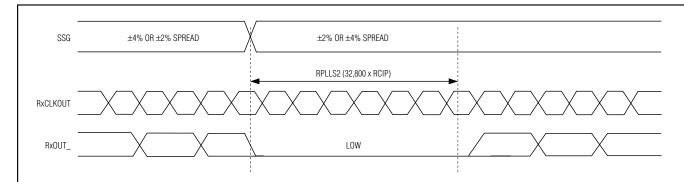


Figure 13. Output Waveforms when Spread Amount is Changed

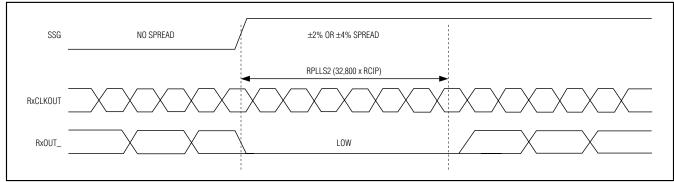


Figure 14. Output Waveforms when Spread is Added

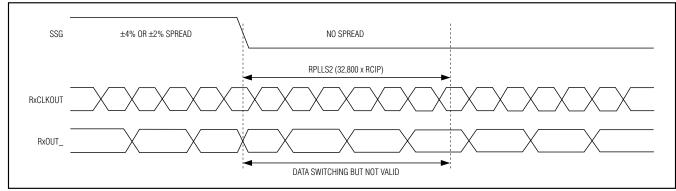


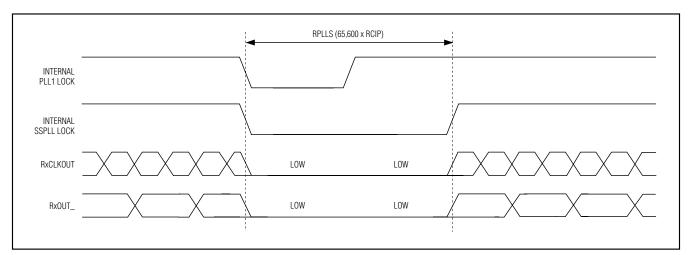
Figure 15. Output Waveforms when Spread is Removed

spread-spectrum PLL locks immediately after (see Figure 16). If the spread-spectrum PLL loses lock, it locks again with only one PLL lock delay (see Figure 17).

AC-Coupling Benefits

Bit errors experienced with DC-coupling (Figure 18) can be eliminated by increasing the receiver commonmode voltage range through AC-coupling. AC-coupling increases the common-mode voltage range of an LVDS receiver to nearly the voltage rating of the capacitor. The typical LVDS driver output is 350mV centered on a 1.25V offset voltage, making single-ended output voltages of 1.425V and 1.075V. An LVDS receiver accepts signals from 0 to 2.4V, allowing approximately \pm 1V common-mode difference between the driver and receiver on a







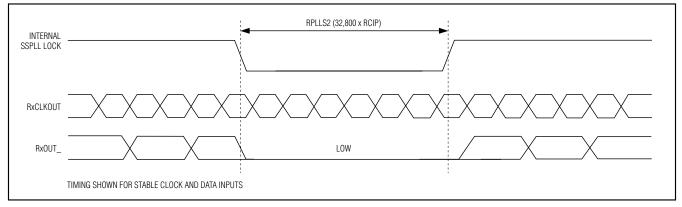


Figure 17. Output Waveforms if Spread-Spectrum PLL Loses Lock and Locks Again

DC-coupled link (2.4V - 1.425V = 0.975V and 1.075V -0V = 1.075V). Common-mode voltage differences may be due to ground potential variation or common-mode noise. If there is more than ±1V of difference, the receiver is not guaranteed to read the input signal correctly and may cause bit errors. AC-coupling filters low-frequency ground shifts and common-mode noise and passes high-frequency data. A common-mode voltage difference up to the voltage rating of the coupling capacitor (minus half the differential swing) is tolerated. DC-balanced coding of the data is required to maintain the differential signal amplitude and limit jitter on an AC-coupled link. A capacitor in series with each output of the LVDS driver is sufficient for AC-coupling. However, two capacitors-one at the serializer output and one at the deserializer input-provide protection in case either end of the cable is shorted to a high voltage.

Applications Information

Selection of AC-Coupling Capacitors

Voltage droop and the DSV of transmitted symbols cause signal transitions to start from different voltage levels. Because the transition time is finite, starting the signal transition from different voltage levels causes timing jitter. The time constant for an AC-coupled link needs to be chosen to reduce droop and jitter to an acceptable level.

The RC network for an AC-coupled link consists of the LVDS receiver termination resistor (R_T), the LVDS driver output resistor (R_O), and the series AC-coupling capacitors (C). The RC time constant for two equal-value series capacitors is (C x (R_T + R_O)) / 2 (Figure 19). The RC time constant for four equal-value series capacitors is (C x (R_T + R_O)) / 4 (Figure 20).



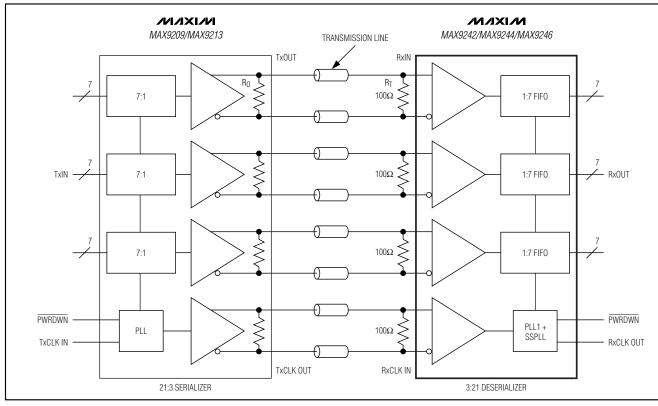


Figure 18. DC-Coupled Link, Non-DC-Balanced Mode

RT is required to match the transmission line impedance (usually 100 Ω) and R_O is determined by the LVDS driver design (the minimum differential output resistance of 78 Ω for the MAX9209/MAX9213 serializers is used in the following example). This condition leaves the capacitor selection to change the system time constant.

In the following example, the capacitor value for a 2% droop is calculated. Jitter due to this droop is then calculated assuming a 1ns transition time:

$$C = -(2 \times t_B \times DSV) / (ln (1 - D) \times (R_T + R_O)) (Eq 1)$$

where:
$$C = AC-coupling capacitor (F)$$

$$t_B = bit time (s)$$

$$DSV = digital sum variation (integer)$$

$$ln = natural log$$

$$D = droop (% of signal amplitude)$$

$$R_T = termination resistor (\Omega)$$

$$R_O = output resistance (\Omega)$$

Equation 1 is for two series capacitors (Figure 19). The bit time (t_B) is the period of the parallel clock divided by 9.

The DSV is 10. See equation 3 for four series capacitors (Figure 20).

The capacitor for 2% maximum droop at 16MHz parallel rate clock is:

 $C = -(2 \times t_B \times DSV) / (ln (1 - D) \times (R_T + R_O))$

 $C = -(2 \times 6.95 \text{ns} \times 10) / (\ln (1 - 0.02) \times (100\Omega + 78\Omega))$ $C = 0.038 \mu \text{F}$

Jitter due to droop is proportional to the droop and transition time:

$$t_J = t_T \times D (Eq 2)$$

where:

 $t_J = jitter (s)$ $t_T = transition time (s) (0 to 100%)$

D = droop (% of signal amplitude)

Jitter due to 2% droop and assumed 1ns transition time is:

tj = 1ns x 0.02

The transition time in a real system depends on the frequency response of the cable driven by the serializer.



M/XI/M

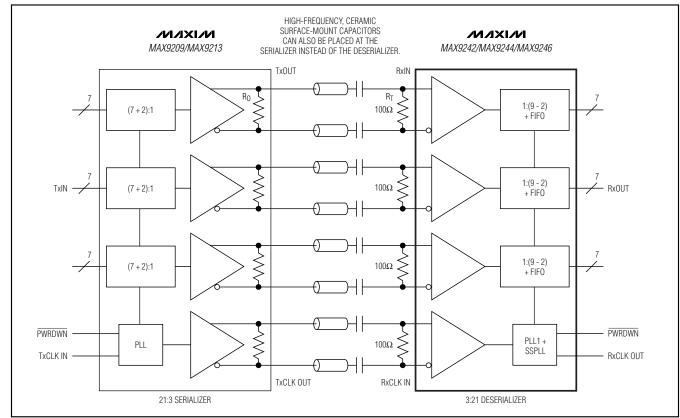


Figure 19. Two Capacitors per Link, AC-Coupled, DC-Balanced Mode

The capacitor value decreases for a higher frequency parallel clock and for higher levels of droop and jitter. Use high-frequency, surface-mount ceramic capacitors.

Equation 1 altered for four series capacitors (Figure 20) is:

$$C = -(4 \times t_B \times DSV) / (ln (1 - D) \times (R_T + R_O)) (Eq 3)$$

Fail-Safe

The MAX9242/MAX9244/MAX9246 have fail-safe LVDS inputs in non-DC-balanced mode (Figure 1). Fail-safe drives the outputs low when the corresponding LVDS input is open, undriven and shorted, or undriven and parallel terminated. The fail-safe on the LVDS clock input drives all outputs low when power is stable. Fail-safe does not operate in DC-balanced mode.

Input Bias and Frequency Detection

In DC-balanced mode, the inverting and noninverting LVDS inputs are internally connected to +1.2V through 42k Ω (min) to provide biasing for AC-coupling (Figure 1). To prevent switching due to noise when the clock input is not driven, bias the clock inputs (RxCLKIN+,

RxCLKIN-) to differential +15mV by connecting a 10k Ω ±1% pullup resistor between the noninverting input and LVDSV_{CC}, and a 10k Ω ±1% pulldown resistor between the inverting input and ground. These bias resistors, along with the 100 Ω ±1% tolerant termination resistor, provide +15mV of differential input. The +15mV bias causes some small degradation of RSKM proportional to the slew rate of the clock input. For example, if the clock transitions 250mV in 500ps, the slew rate of 0.5mV/ps reduces RSKM by 30ps.

Unused LVDS Data Inputs

In non-DC-balanced mode, leave unused LVDS data inputs open. In non-DC-balanced mode, the input failsafe circuit drives the corresponding outputs low, and no pullup or pulldown resistors are needed. In DC-balanced mode, at each unused LVDS data input, pull the inverting input up to LVDSV_{CC} using a 10k Ω resistor, and pull the noninverting input down to ground using a 10k Ω resistor. Do not connect a termination resistor. The pullup and pulldown resistors drive the corresponding outputs low and prevent switching due to noise.



MAX9242/MAX9244/MAX9246

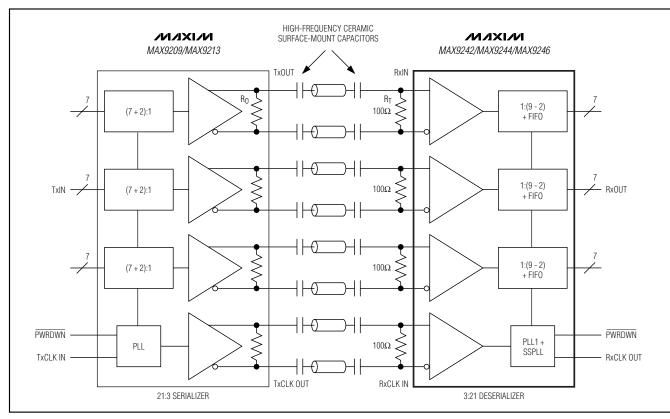


Figure 20. Four Capacitors per Link, AC-Coupled, DC-Balanced Mode

Link Power-Up Sequence

The recommended link power-up sequence is to power up the serializer, wait until the serializer PLL locks, and then power up the deserializer. This sequence prevents the deserializer from seeing an undriven or unstable input when powering up.

PWRDWN

Driving PWRDWN low puts the outputs in high impedance, stops the PLL, and reduces supply current to 50µA or less. Driving PWRDWN high drives the outputs low until the PLL locks. The outputs of two deserializers can be bused to form a 2:1 mux with the outputs controlled by PWRDWN. Wait 100ns between disabling one deserializer (driving PWRDWN low) and enabling the second one (driving PWRDWN high) to avoid contention of the bused outputs.

Power-Supply Bypassing

There are separate on-chip power domains for digital circuits, outputs, PLL, and LVDS inputs. Bypass each VCC, VCCO, PLLVCC, and LVDSVCC with high-frequency,

surface-mount ceramic $0.1\mu F$ and $0.001\mu F$ capacitors in parallel as close to the device as possible, with the smallest value capacitor closest to the supply pin.

Cables and Connectors

Interconnect for LVDS typically has a differential impedance of 100Ω . Use cables and connectors that have matched differential impedance to minimize impedance discontinuities.

Twisted-pair and shielded twisted-pair cables offer superior signal quality compared to ribbon cable and tend to generate less EMI due to magnetic field canceling effects. Balanced cables pick up noise as common mode, which is rejected by the LVDS receiver.

Board Layout

Keep the LVTTL/LVCMOS outputs and LVDS input signals separated to prevent crosstalk. A four-layer PC board with separate layers for power, ground, LVDS inputs, and digital signals is recommended. Layout PC board traces for 100 Ω differential characteristic impedance. The trace dimensions depend on the type of



trace used (microstrip or stripline). Note that two 50Ω PC board traces do not have 100Ω differential impedance when brought close together—the impedance goes down when the traces are brought closer.

Route the PC board traces for an LVDS channel (there are two conductors per LVDS channel) in parallel to maintain the differential characteristic impedance. Place the termination resistor at the end of the PC board traces within a 1/4 inch of the LVDS receiver input. Avoid vias. If vias must be used, use only one pair per LVDS channel and place the via for each line at the same point along the length of the PC board traces. This way, any reflections will occur at the same time. Do not make vias into test points for ATE. Make LVDS clock and data pairs the same length on the PC board to avoid pair-to-pair skew. Make the PC board traces that make up a differential pair the same length to avoid skew within the differential pair.

5V-Tolerant Input

PWRDWN is 5V tolerant and is internally pulled down to GND. SSG and DCB are not 5V tolerant. The input voltage range for SSG and DCB is nominally ground to V_{CC}.

Skew Margin (RSKM)

Skew margin (RSKM) is the time allowed for degradation of the serial-data sampling setup and hold times by sources other than the deserializer. The deserializer sampling uncertainty is accounted for and does not need to be subtracted from RSKM. The main outside contributors of jitter and skew that subtract from RSKM are interconnect intersymbol interference, serializer pulse position uncertainty, and pair-to-pair path skew.

Vcco Output Supply and Power Dissipation

The outputs have a separate supply (V_{CCO}) for interfacing to systems with 1.8V to 5V nominal input logic levels. The *DC Electrical Characteristics* table gives the maximum supply current for V_{CCO} = 3.6V with 8pF load at several switching frequencies with all outputs switching in the worst-case switching pattern. The approximate incremental supply current for V_{CCO} other than 3.6V with the same 8pF load and worst-case pattern can be calculated using:

 $I_{I} = C_{T}V_{I} 0.5f_{C} \times 21 \text{ (data outputs)}$ $+ C_{T}V_{I}f_{C} \times 1 \text{ (clock output)}$

where:

I_I = incremental supply current

 C_T = total internal (C_{INT}) and external (C_L) load capacitance

V_I = incremental supply voltage

 f_{C} = output clock switching frequency

The incremental current is added to (for V_{CCO} > 3.6V) or subtracted from (for V_{CCO} < 3.6V) the *DC Electrical Characteristics* table maximum supply current. The internal output buffer capacitance is $C_{INT} = 6pF$. The worst-case pattern switching frequency of the data outputs is half the switching frequency of the output clock.

In the following example, the incremental supply current of the MAX9244 in spread and DC-balanced mode is calculated for $V_{CCO} = 5.5V$, f_C = 34MHz, and C_L = 8pF:

$$V_{I} = 5.5V - 3.6V = 1.9V$$

$$CT = CINT + CL = 6pF + 8pF = 14pF$$

where:

 $I_I = C_T V_I 0.5 f_C \times 21$ (data outputs) + $C_T V_I f_C \times 1$ (clock output)

 $I_{I} = (14 pF \times 1.9 V \times 0.5 \times 34 MHz \times 21) + (14 pF \times 1.9 V \times 34 MHz)$

 $I_{I} = 9.5mA + 0.9mA = 10.4mA.$

The maximum supply current in DC-balanced mode for $V_{CC} = V_{CCO} = 3.6V$ at $f_C = 34$ MHz is 125mA (from the *DC Electrical Characteristics* table). Add 10.4mA to get the total approximate maximum supply current at $V_{CCO} = 5.5V$ and $V_{CC} = 3.6V$.

If the output supply voltage is less than $V_{CCO} = 3.6V$, the reduced supply current can be calculated using the same formula and method.

At high switching frequency, high supply voltage, and high capacitive loading, power dissipation can exceed the package power dissipation rating. Do not exceed the maximum package power dissipation rating. See the *Absolute Maximum Ratings* for maximum package power dissipation capacity and temperature derating.

Rising- or Falling-Edge Output Strobe

The MAX9242 has a rising-edge output strobe, which latches the parallel output data into the next chip on the rising edge of RxCLKOUT. The MAX9244/MAX9246 have a falling-edge output strobe, which latches the parallel output data into the next chip on the falling edge of RxCLKOUT. The deserializer output strobe polarity does not need to match the serializer input strobe polarity.

Three-Level Logic Inputs

SSG and DCB (DCB mid level is reserved) are threelevel-logic inputs. A logic-high input voltage must be greater than +2.5V and a logic-low input voltage must be less than +0.8V. A mid-level logic is recognized by the MAX9242/MAX9244/MAX9246 when the input is left open or connected to a driver in a high-impedance state. A weak inverter on the input stage of SSG and



DCB provides the proper mid-level voltage under conditions of low input current. The mid-level input current must not be greater than $\pm 10\mu$ A, and the mid-level logic state cannot be driven with an external voltage source.

IEC 61000-4-2 Level 4 and ISO 10605 ESD Protection

The MAX9242/MAX9244/MAX9246 ESD tolerance is rated for Human Body Model, IEC 61000-4-2 and ISO 10605. The ISO 10605 and IEC 61000-4-2 standards specify ESD tolerance for electronic systems. All LVDS inputs on the MAX9242/MAX9244/MAX9246 meet ISO 10605 ESD protection at ±30kV Air-Gap Discharge and ±6kV Contact Discharge and IEC 61000-4-2 ESD protection at ±15kV Air-Gap Discharge and ±8kV Contact Discharge. All other pins meet the Human Body Model ESD tolerance of ±2.5kV. The Human Body Model discharge components are C_S = 100pF and R_D = 1.5k Ω (Figure 21). The IEC 61000-4-2 discharge components are C_S = 330pF and R_D = 2k Ω (Figure 23).

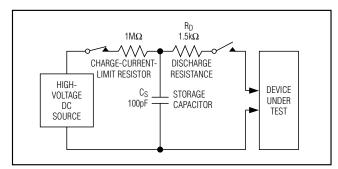


Figure 21. Human Body ESD Test Circuit

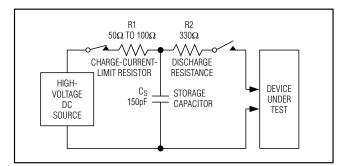


Figure 22. IEC 61000-4-2 Contact Discharge ESD Test Circuit

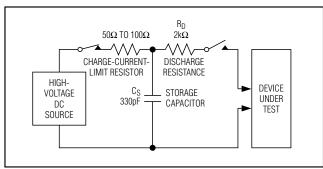
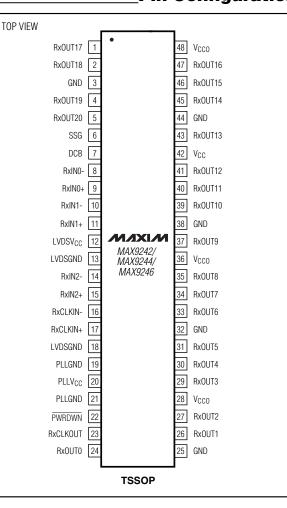


Figure 23. ISO 10605 Contact Discharge ESD Test Circuit



Pin Configuration

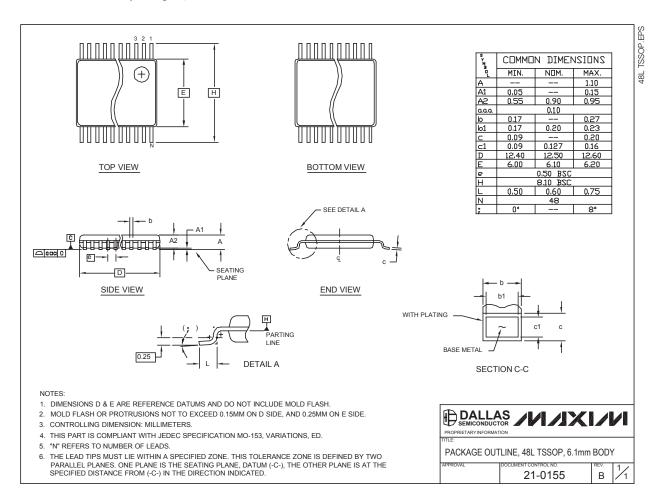
Chip Information

PROCESS: CMOS

MAX9242/MAX9244/MAX9246

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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MAX9242/MAX9244/MAX9246

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